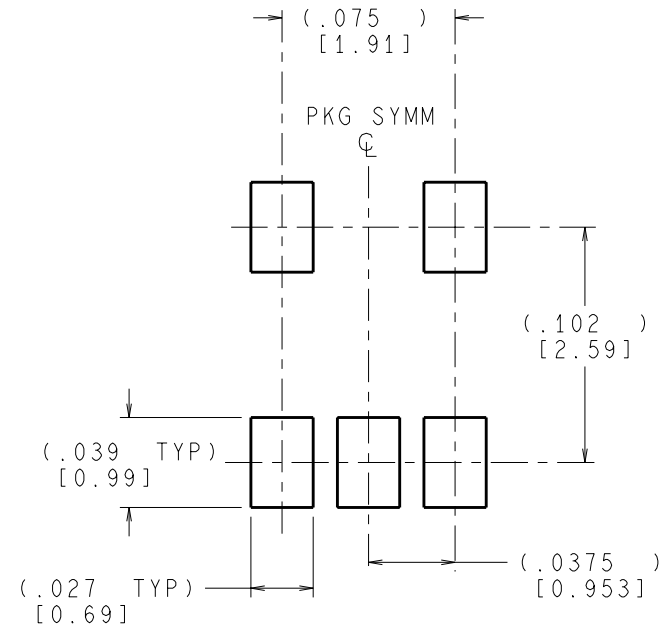
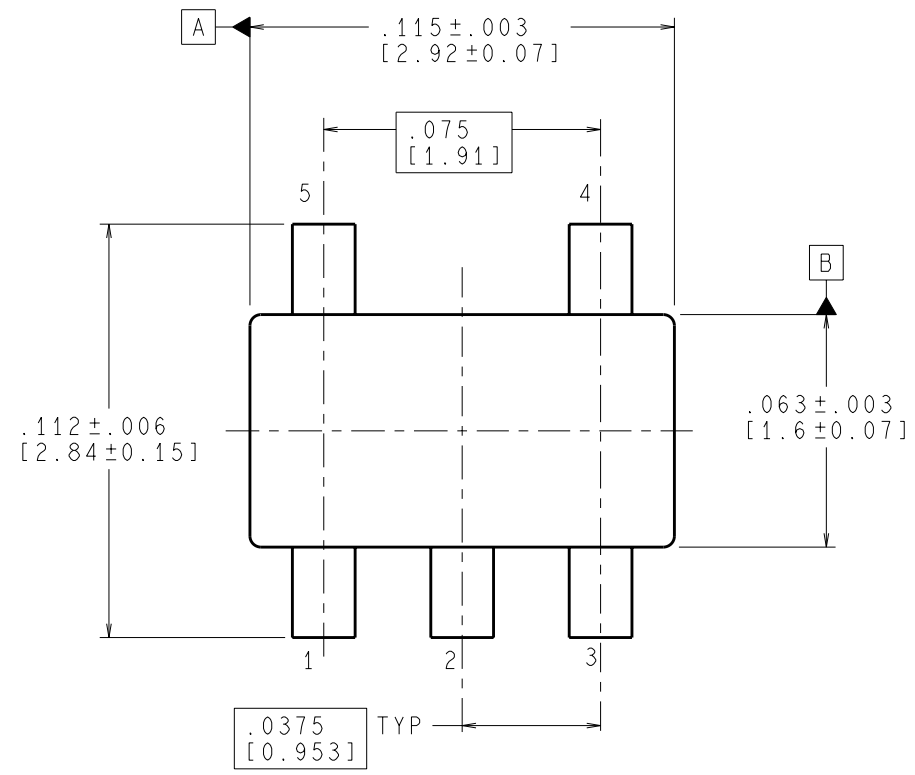
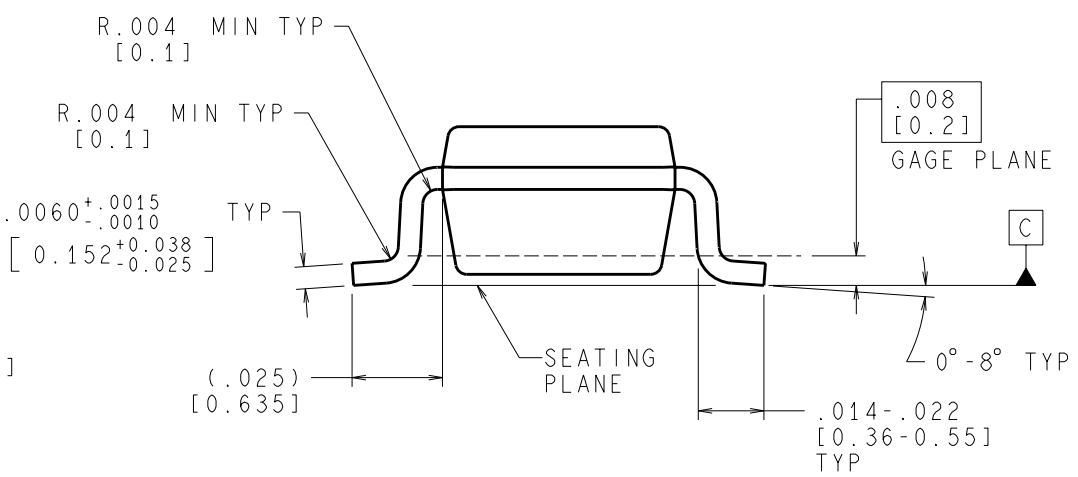
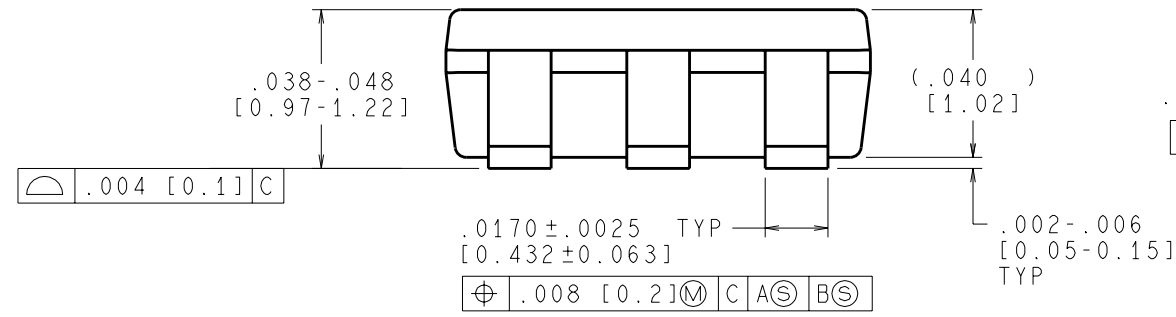


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12343	01/07/2000	TL/RW



LAND PATTERN RECOMMENDATION



**CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS**

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH TO BE 200 MICRONS [5.08 MICROMETERS] MINIMUM TIN/LEAD (SOLDER) ON COPPER.
 - REFERENCE JEDEC REGISTRATION MO-178, VARIATION AA, DATED JANUARY 1999.

APPROVALS	DATE	National Semiconductor		
DRAWN T. LEQUANG	01/07/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. MARTA SUCHY	01/07/2000	MOLDED SOT-23, .115 X .063 X .040 IN BODY, 5 LD, .0375 IN PITCH		
ENGR. CHK. RANDY WALBERG	01/07/2000			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	(SC)MKT-MF05A	A
FORMERLY:			SHEET 1 of 1	